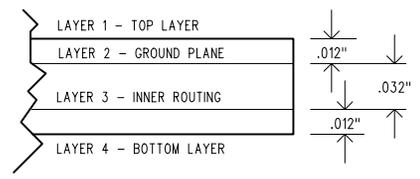
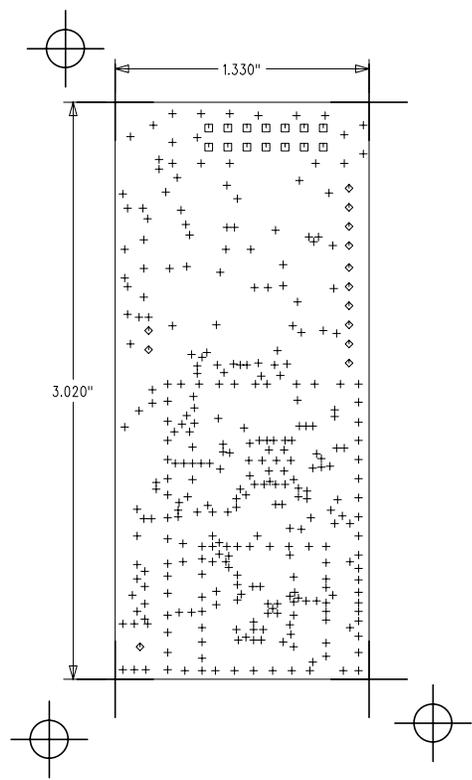


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FABRICATION NOTES:

1. ALL BOARD DIMENSIONS IN INCHES. TOLERANCE = +/-0.005" UNLESS NOTED OTHERWISE.
2. BOARD TO BE FABRICATED TO IPC-A-600, CURRENT REVISION, SPECIFICATIONS LISTED HERE SUPERCEDE APPLICABLE IPC SPECIFICATIONS.
3. BOARD MATERIAL - FR-4 GRADE GLASS EPOXY, 0.065" +.003"/-.004" THICKNESS MEASURED OVER COPPER MINIMUM FLAMMABILITY RATING UL 94V-0
4. OUTER LAYER FINISHED COPPER THICKNESS 0.0028" (2 OZ). INNER LAYER COPPER THICKNESS 0.0014" (1 OZ).
5. SOLDER MASK OVER BARE COPPER, LPI, CLASS 2 GEN. INDUSTRIAL REGISTRATION +/-0.004", GREEN. NO COVERAGE ON SOLDER PADS PERMITTED.
6. FINISH-TIN/LEAD REFLOWED OR HOT AIR SOLDER LEVELED-0.0002" TO 0.002" PLATING THICKNESS. NO EXPOSED BARE COPPER PERMITTED.
7. SILKSCREEN WHITE EPOXY NON-CONDUCTIVE INK OVER GREEN SOLDERMASK, TOP SIDE ONLY. SILKSCREEN SHOULD BE TRIMMED OFF ANY SOLDERED ENTITY.
8. HOLE CENTERS AND PAD CENTERS TO BE CONCENTRIC WITHIN 0.005"



DRILL CHART

| SIZE | QTY | SYM | PLTD | TOL |
|-------|-----|-----|------|----------|
| 0.01 | 314 | + | YES | +/-0.002 |
| 0.035 | 14 | □ | YES | +/-0.002 |
| 0.042 | 13 | ◇ | YES | +/-0.002 |

ARTWORK/FABRICATION FILES

- LAYER 1 - TOP SIDE ROUTING - COPPER1.PHO
- LAYER 2 - INNER 2 ROUTING - COPPER2.PHO
- LAYER 3 - INNER 3 ROUTING - COPPER3.PHO
- LAYER 4 - BOTTOM SIDE ROUTING - COPPER4.PHO
- TOP SIDE SOLDERMASK - TOPMASK.PHO
- BOTTOM SIDE SOLDERMASK - BOTMOMASK.PHO
- TOP SIDE SILKSCREEN - TOPSILK.PHO

- NC DRILL FILE - NCDRILL.DRL
- APERTURE LIST - APERTURES.REP

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| CHECKED BY: MARK WOLSKI | DATE: 12-01-2004 | PROJECT: TI HP FHSS TRANSCEIVER #056 | | |
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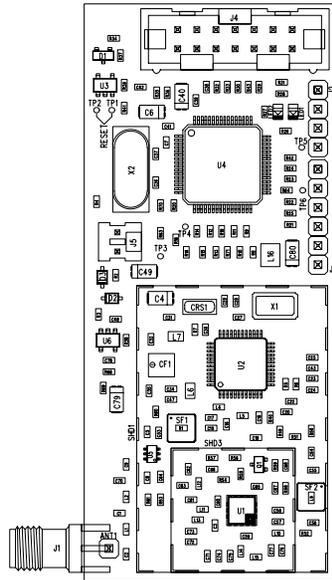
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TOP SIDE ASSEMBLY NOTES/ARTWORK FILES:
TOP SIDE SOLDER PASTE MASK - TOPPASTE.PHO

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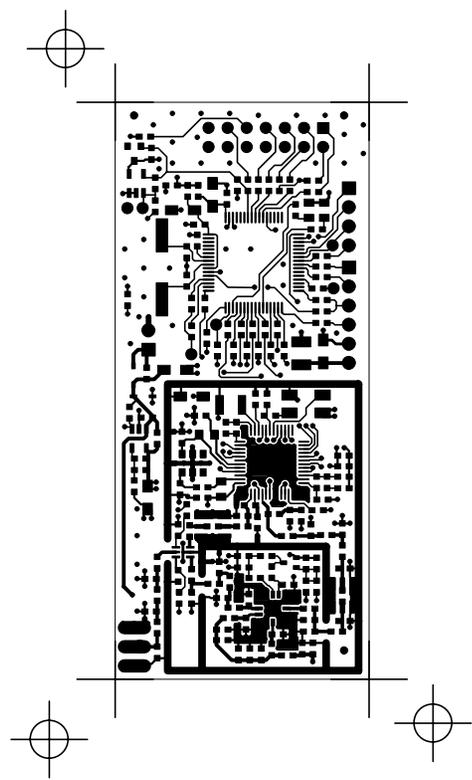
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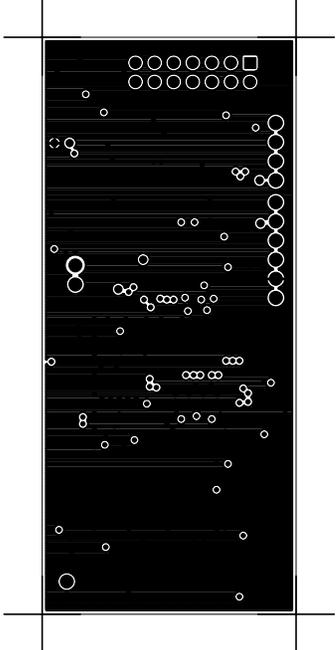
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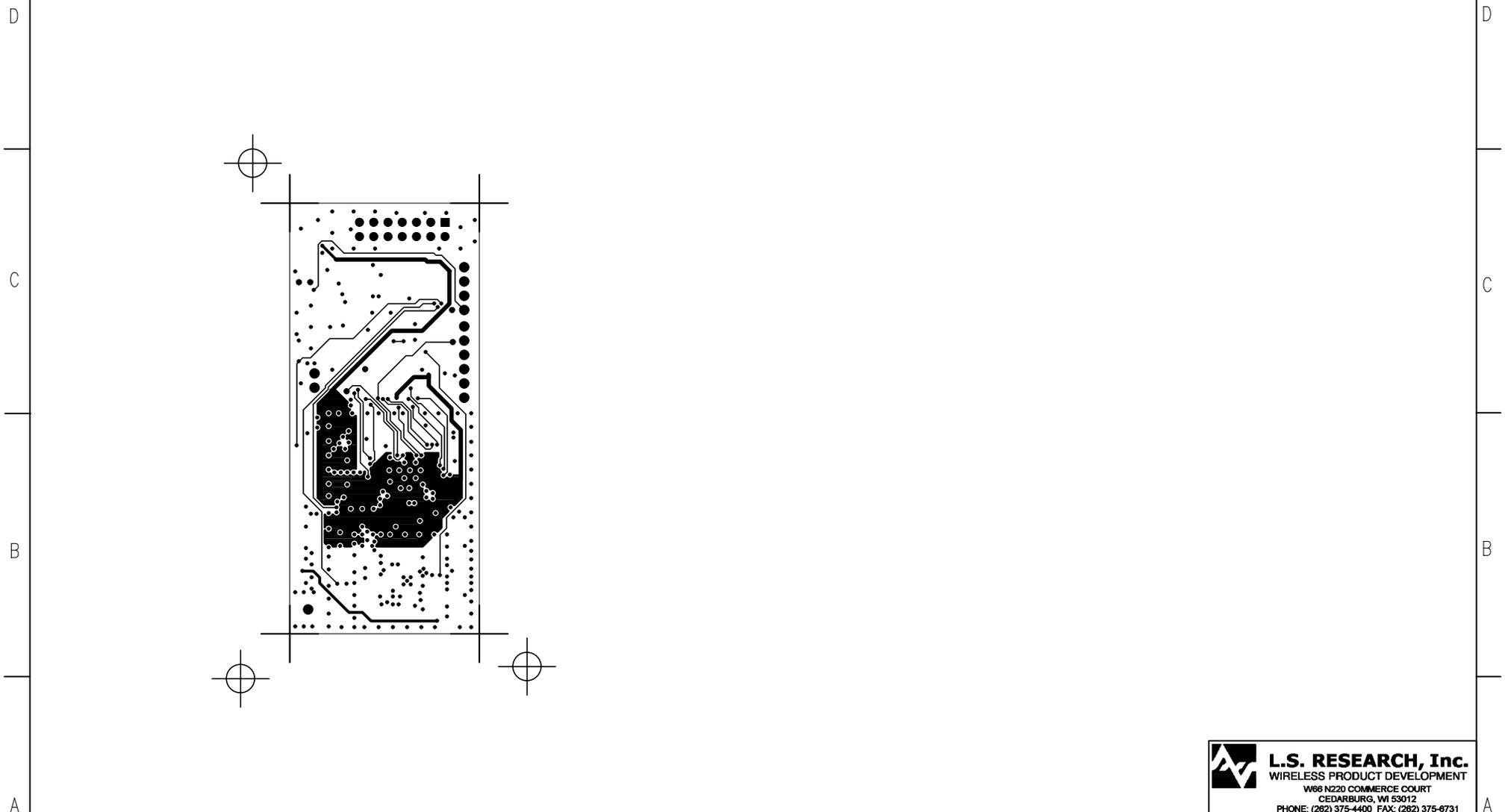


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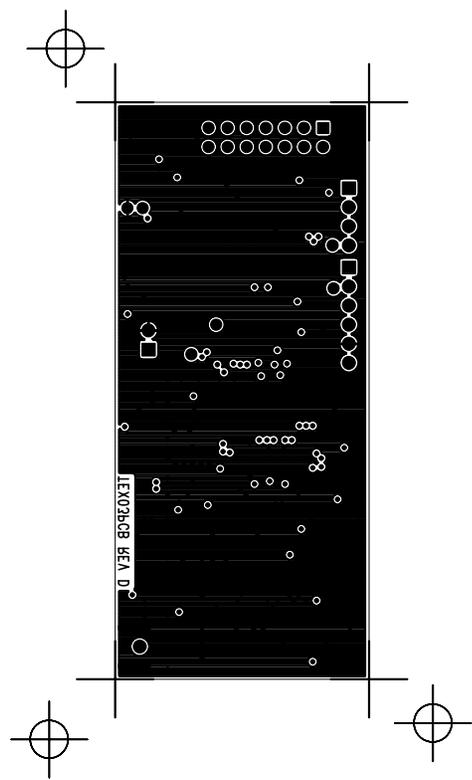
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| DRAWN BY: DS/MH | DATE: 07-07-2004 | TITLE: - COPPER, LAYER 3 | | |
| CHECKED BY: MARK WOLSKI | DATE: 12-01-2004 | PROJECT: TI HP FHSS TRANSCEIVER #056 | | |
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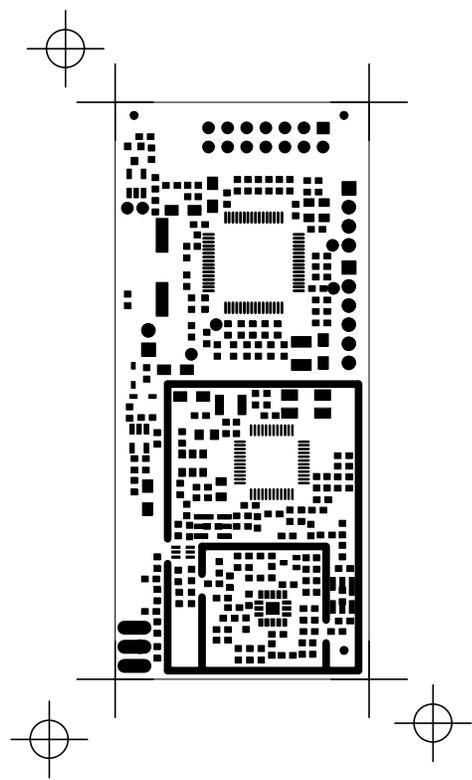
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| DRAWN BY: DS/MH | DATE: 07-07-2004 | TITLE: - COPPER, LAYER 4 | | |
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| APPROVED BY: | DATE: | SIZE: A | DRAWING NO: TEX03LR2 | REV: D |
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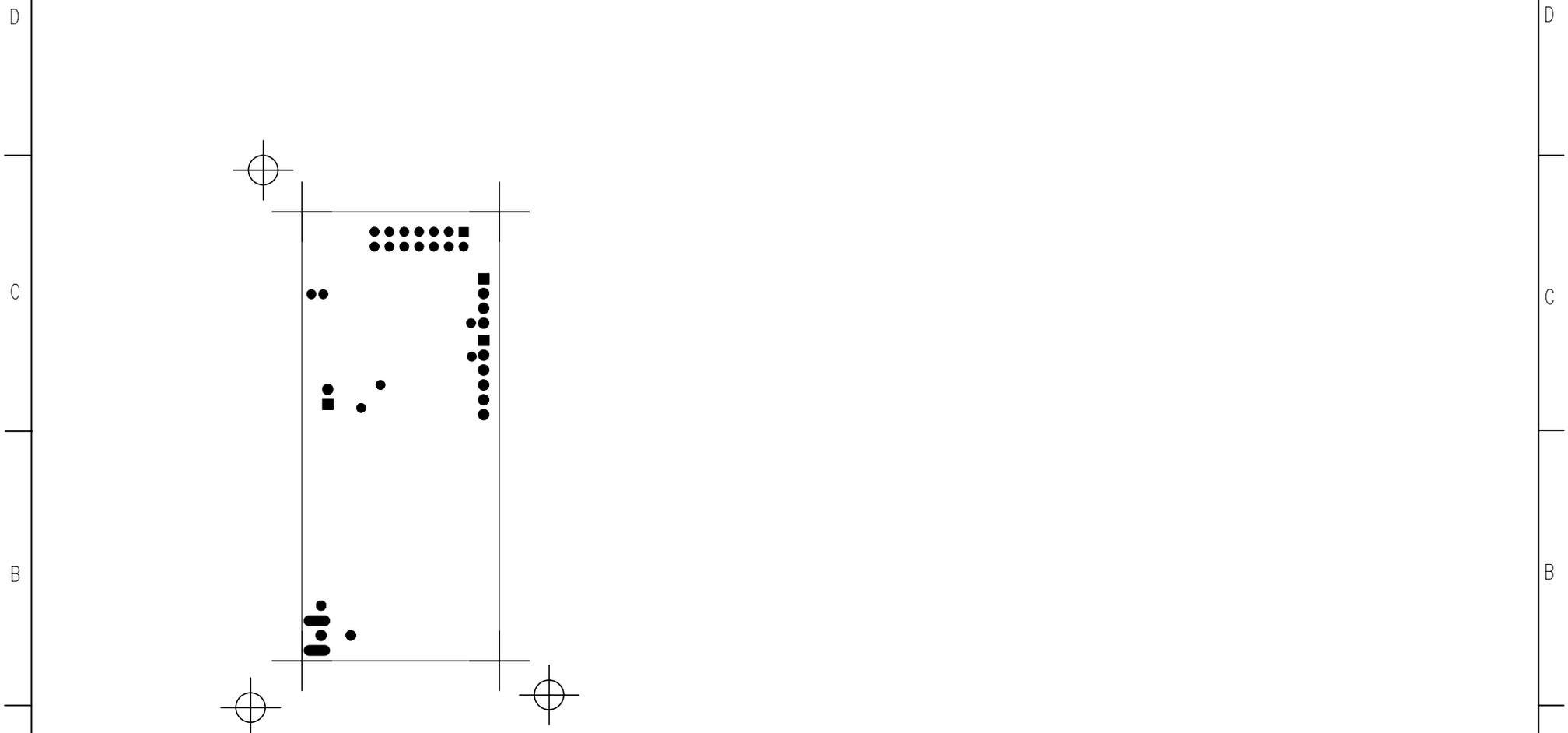


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|----------------------------|---------------------|--------------------------------------|
| DRAWN BY: DS/MH | DATE: 07-07-2004 | TITLE: - TOP SOLDERMASK |
| CHECKED BY: MARK WOLSKI | DATE: 12-01-2004 | PROJECT: TI HP FHSS TRANSCEIVER #056 |
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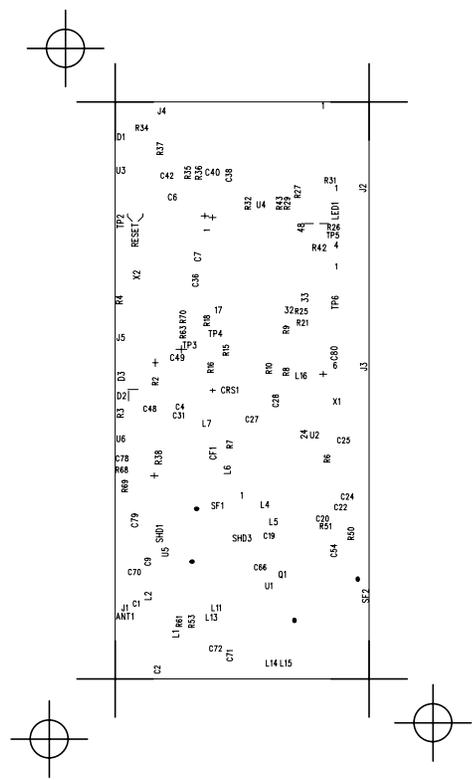
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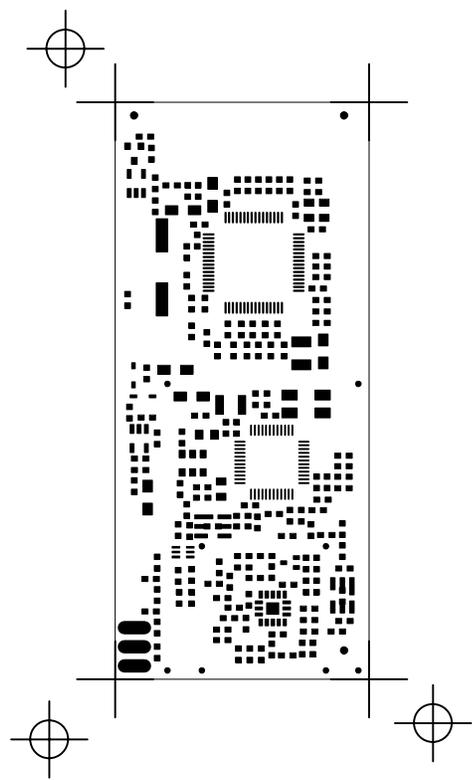
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